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(54) **METHOD FOR MOUNTING SEMICONDUCTOR PACKAGE COMPONENT, AND STRUCTURE HAVING SEMICONDUCTOR PACKAGE COMPONENT MOUNTED THEREIN**

VERFAHREN ZUR MONTAGE EINER HALBLEITERPAKETKOMPONENTE UND STRUKTUR MIT DARAUF MONTIERTER HALBLEITERPAKETKOMPONENTE

PROCÉDÉ DE MONTAGE D'UN COMPOSANT DE BOÎTIER POUR SEMI-CONDUCTEUR, ET STRUCTURE DANS LAQUELLE EST MONTÉ CET ÉLÉMENT

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(73) Proprietor: **Panasonic Intellectual Property
Management Co., Ltd.**
Osaka-shi, Osaka 540-6207 (JP)

(72) Inventors:
• **Ohashi, Naomichi**
Osaka 540-6207 (JP)
• **Yamaguchi, Atsushi**
Osaka 540-6207 (JP)
• **Kishi, Arata**
Osaka 540-6207 (JP)
• **Udaka, Masato**
Osaka 540-6207 (JP)

• **Tokii, Seiji**
Osaka 540-6207 (JP)

(74) Representative: **Grünecker Patent- und
Rechtsanwälte**
PartG mbB
Leopoldstraße 4
80802 München (DE)

(56) References cited:
JP-A- 2002 198 384 JP-A- 2002 198 384
JP-A- 2003 197 681 JP-A- 2008 166 377
JP-A- 2009 021 465 JP-A- 2009 021 465
US-A- 5 814 401 US-A1- 2004 238 925
US-A1- 2004 262 368 US-A1- 2008 308 930

• -: **"Epoxy Adhesive Application Guide", , 1**
January 2016 (2016-01-01), XP055348601,
Retrieved from the Internet:
URL: http://www.epotek.com/site/files/brochures/pdfs/adhesive_application_guide.pdf
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